Customer Information Notification

202305013I : Removal of Cold (-40C) Test Insertion for FXLS8964AF and FXLS8968AF Products

Note: This notice is NXP Company Proprietary.

Issue Date: Jun 01, 2023 **Effective date:Jun 02, 2023**

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Management summary
Removal of Cold (-40C) test insertion for FXLS8964AF and FXLS8968AF products.

Change Category

[ ]Wafer Fab Process	[ ]Assembly Process	[ ]Product Marking	[X]Test Process	[ ]Design
[ ]Wafer Fab Materials	[ ]Assembly Materials	[ ]Mechanical Specification	[ ]Test Equipment	[ ]Errata
[ ]Wafer Fab Location	[ ]Assembly Location	[ ]Packing/Shipping/Labeling	[ ]Test Location	[ ]Electrical spec./Test coverage
[ ]Firmware	[ ]Other			

PCN Overview
Description

Removal of Cold (-40C) test insertion for FXLS8964AF and FXLS8968AF products.

Reason
Supply assurance.

Identification of Affected Products
Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision
No impact to existing datasheet

Disposition of Old Products
Existing inventory will be shipped until depleted

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.
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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
FXLS8964AFR3	935377074471	FXLS8964AFR3	3axis 2/4/8/16g 2X2DFN10	(V)SON10COLWF	SOT1615-3	RFS	No	BLC6
FXLS8968AFR3	935424252471	FXLS8968AFR3	3axis 2/4/8/16g 2X2DFN10	(V)SON10COLWF	SOT1615-3	RFS	No	BLC6